

Amendments to the Claims:

This listing of claims replaces all prior versions, and listings, of claims in this application.

Listing of Claims:

1. (Currently Amended) A semiconductor device comprising:

a semiconductor chip;

a first external connection electrode connected to the chip;

a second external connection electrode connected to the chip; and

a resin package that covers the chip and has a mounting surface, the resin package also including a first side surface, a second side surface adjacent to the first side surface, a third side surface opposite to the second side surface, and a fourth side surface opposite to the first side surface;

wherein each of the first and second electrodes includes a thick portion and a thin portion, the thick portion being exposed to outside only at the mounting surface of the package, the thick portion being not exposed at ~~any other surface~~ the first to fourth surfaces of the package; and

wherein the thin portion of the first electrode includes a first extension and a second extension, the first extension being spaced from the mounting surface of the package and exposed at the first side surface of the package, the second extension being spaced from the mounting surface and the first side surface of the package while extending toward the second electrode, the thin portion of the second electrode being spaced from the mounting surface of the package and exposed at the fourth side surface of the package.

2. (Previously Presented) The semiconductor device according to claim 1, wherein the first electrode has a flat upper surface for mounting the chip, the thick portion of the first electrode including a downward projection extending from the upper surface to the mounting surface of the package.

3. (Previously Presented) The semiconductor device according to claim 2, wherein the projection includes a bottom surface exposed to outside at the mounting surface of the package and four side surfaces entirely covered with the package.

4. (Original) The semiconductor device according to claim 1, wherein the thick portion and the thin portion are formed of a same material and integral with each other.

5. (Previously Presented) The semiconductor device according to claim 1, wherein the first electrode includes two thick portions spaced from each other and a thin portion connecting the thick portions, both of the two thick portions being exposed to outside only at the mounting surface of the package.

6-7. (Cancel)

8. (Cancelled)

9. (Previously Presented) The semiconductor device according to claim 1, wherein the first external connection electrode include a first flat surface for mounting the chip, the second external connection electrode including a second flat surface for connection to the chip via a wire, the first surface and the second surface being flush with each other.

10. (Cancelled)

11. (Cancel)

12. (New) The semiconductor device according claim 1, wherein the second extension of the first external connection electrode projects toward and is exposed at the second side surface of the package.

13. (New) The semiconductor device according to claim 1, wherein the first external connection electrode further includes a third extension projecting toward and exposed at the third side surface of the package.